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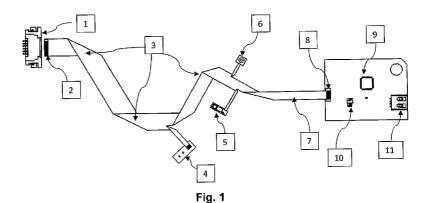
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(54) Title: A RIGID-FLEX CIRCUIT BOARD AND MANUFACTURING METHOD



(57) Abstract: Disclosed herein is a cost effective rigid- flex circuit board comprising a flexible section which contents at least one flexible flat cable for interconnect, and a plurality of rigid sections which consists of at least one rigid printed circuit board (8) for components mounting. The improved flexible flat cable comprising at least one layer of flat wires laminated with a plurality of insulating material. The flat wires having non-uniform width and pitch are folded with different angle along the length to resemble wiring patterns of a typical flexible printed circuit board. The rigid section consists of at least one piece of rigid printed circuit board having at least one layer of circuit pattern.



